

In the Claims

Claims 1-50 (canceled).

Claim 51 (previously presented): A method of forming a plurality of microelectronic lids, comprising:

forming a lid stock material into a shape of a bar having a side, and a groove extending along the side;

after forming the lid stock material into the shape, cutting the bar into a plurality of separated microelectronic lids; and

wherein the lid stock material comprises aluminum or copper, and further comprising electroplating the separated microelectronic lids with nickel.

Claim 52 (previously presented): The method of claim 51 wherein the forming the lid stock material into the shape comprises extruding the lid stock material into the shape.

Claim 53 (previously presented): The method of claim 51 wherein the forming the lid stock material into the shape comprises:

providing a bar of the lid stock material that lacks the groove in the side; and
machining the groove into the side of the bar.

Claim 54 (previously presented): The method of claim 51 wherein the lid stock material comprises aluminum.

Claim 55 (previously presented): The method of claim 51 wherein the lid stock material comprises copper.

Claim 56 (previously presented): The method of claim 51 further comprising incorporating at least one of the microelectronic lids into a microelectronic package, the incorporating comprising:

providing a chip supported by a base; and

adhering the microelectronic lid to the base and over the chip; the chip accordingly being packaged between the microelectronic lid and the base.